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14 GBPS FAST RISE TIME 1:2 FANOUT BUFFER

Typical Applications

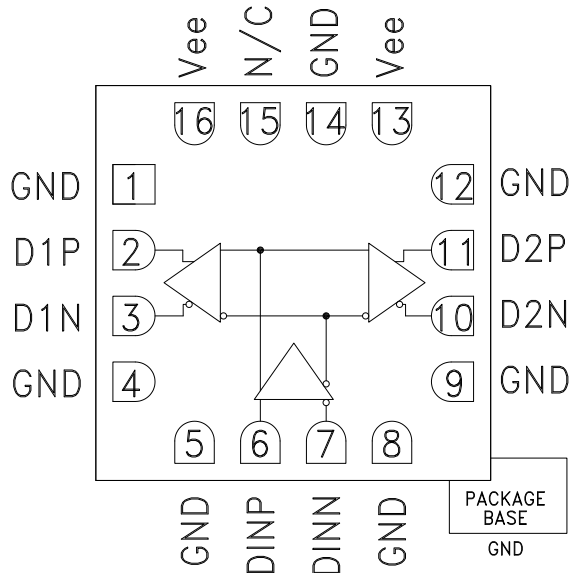
The HMC724LC3 is ideal for:

- 16 G Fiber Channel
- RF ATE Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 14 Gbps
- Clock Buffering up to 14 GHz

Features

- Inputs Terminated Internally to 50 Ohms
- Differential Inputs are DC Coupled
- Propagation Delay: 110 ps
- Fast Rise and Fall Times: 19 / 18 ps
- Power Dissipation: 300 mW
- 16 Lead Ceramic 3x3 mm SMT Package: 9 mm²

Functional Diagram



General Description

The HMC724LC3 is a 1:2 Fanout Buffer designed to support data transmission rates up to 14 Gbps, and clock frequencies as high as 14 GHz. All differential inputs and outputs are DC coupled and terminated on chip with 50 Ohm resistors to ground. The outputs may be used in either single ended or differential modes, and should be AC or DC coupled into 50 Ohm resistors connected to ground.

All differential inputs to the HMC724LC3 are CML and terminated on-chip with 50 Ohms to the positive supply, GND, and may be DC or AC coupled. The differential CML outputs are source terminated to 50 Ohms and may also be AC or DC coupled. Outputs can be connected directly to a 50 Ohm ground-terminated system or drive devices with CML logic input. The HMC724LC3 operates from a single -3.3 V supply and is available in ROHS-compliant 3x3 mm SMT package.

Electrical Specifications, $T_A = +25\text{ }^\circ\text{C}$, $V_{ee} = -3.3\text{ V}$

| Parameter | Conditions | Min. | Typ. | Max | Units |
|--------------------------|----------------------------|------|---------|------|-------|
| Power Supply Voltage | | -3.6 | -3.3 | -3.0 | V |
| Power Supply Current | | | 90 | | mA |
| Maximum Data Rate | | | 14 | | Gbps |
| Maximum Clock Rate | | | 14 | | GHz |
| Input Voltage Range | | -1.5 | | 0.5 | V |
| Input Differential Range | | 0.1 | | 2.0 | Vp-p |
| Input Return Loss | Frequency <14 GHz | | 10 | | dB |
| Output Amplitude | Single-Ended, peak-to-peak | | 550 | | mVp-p |
| | Differential, peak-to-peak | | 1100 | | mVp-p |
| Output High Voltage | | | -10 | | mV |
| Output Low Voltage | | | -560 | | mV |
| Output Rise / Fall Time | Single-Ended, 20% - 80% | | 19 / 18 | | ps |

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HMC724* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC724LC3 Evaluation Board

DOCUMENTATION

Data Sheet

- HMC724 Data Sheet

REFERENCE MATERIALS

Quality Documentation

- HMC Legacy PDN: PCN0811003
- Package/Assembly Qualification Test Report: LC3, LC3B, LC3C (QTR: 2014-00376 REV: 01)
- Semiconductor Qualification Test Report: BiCMOS-C (QTR: 2013-00241)

DESIGN RESOURCES

- HMC724 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC724 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

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Submit feedback for this data sheet.



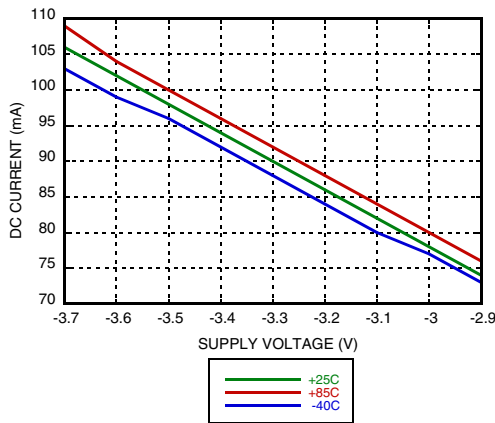
**14 GBPS FAST RISE TIME
1:2 FANOUT BUFFER**

Electrical Specifications (continued)

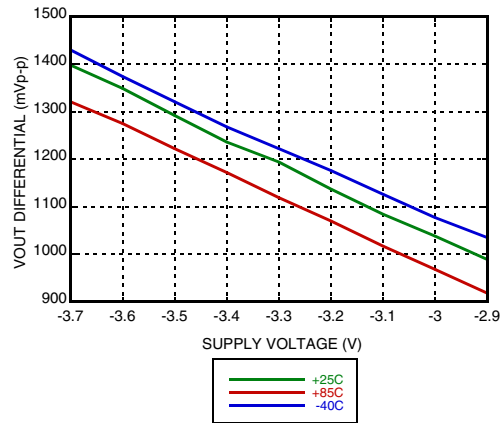
| Parameter | Conditions | Min. | Typ. | Max | Units |
|--------------------------------|--|------|------|-----|--------|
| Output Return Loss | Frequency <14 GHz | | 10 | | dB |
| Small Signal Gain | | | 27 | | dB |
| Random Jitter J_R | rms | | 0.2 | | ps rms |
| Deterministic Jitter, J_D | $\delta - \delta$, 2^{15} -1 PRBS input [1] | | 2 | 6 | ps |
| Propagation Delay, t_d | | | 110 | | ps |
| D1 to D2 Data Skew, t_{SKEW} | | | <2 | | ps |

[1] Deterministic jitter measured at 13 GHz with a 300 mVp-p, 2^{15} -1 PRBS input sequence.

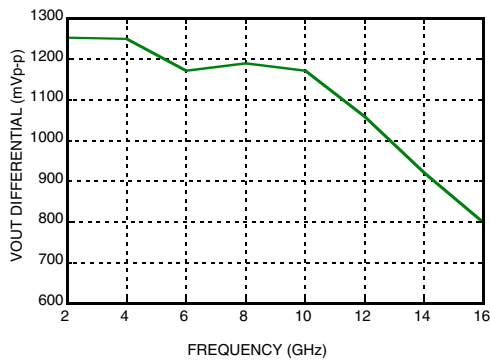
DC Current vs. Supply Voltage [1]



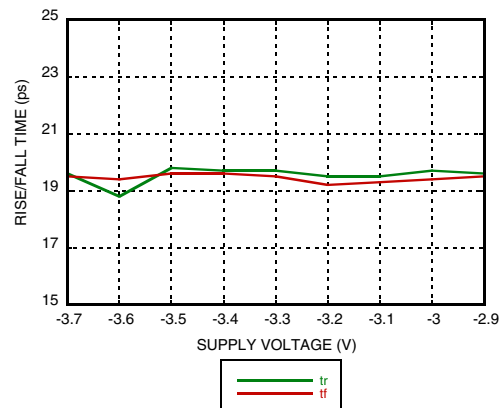
Output Differential Voltage vs. Supply Voltage [2]



Output Differential Voltage vs. Frequency [3]



Rise / Fall Time vs. Supply [1]



[1] Data rate = 13 Gbps

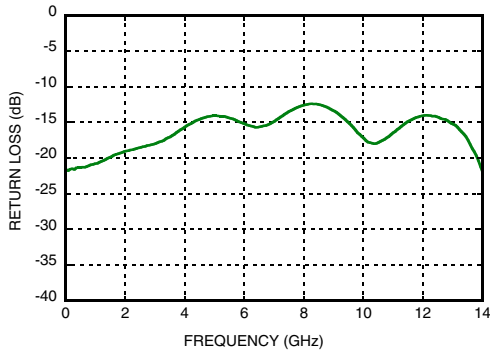
[2] Frequency = 10 GHz

[3] Vee = 3.3 V

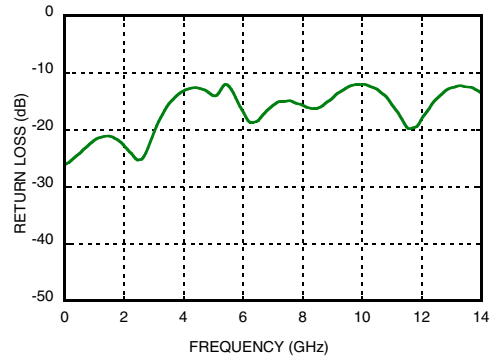


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Output Return Loss vs. Frequency



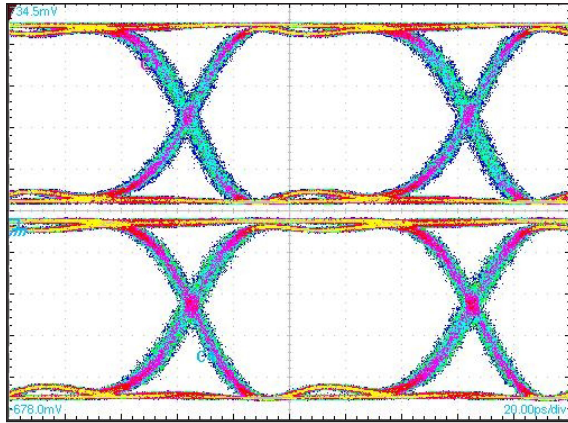
Input Return Loss vs. Frequency





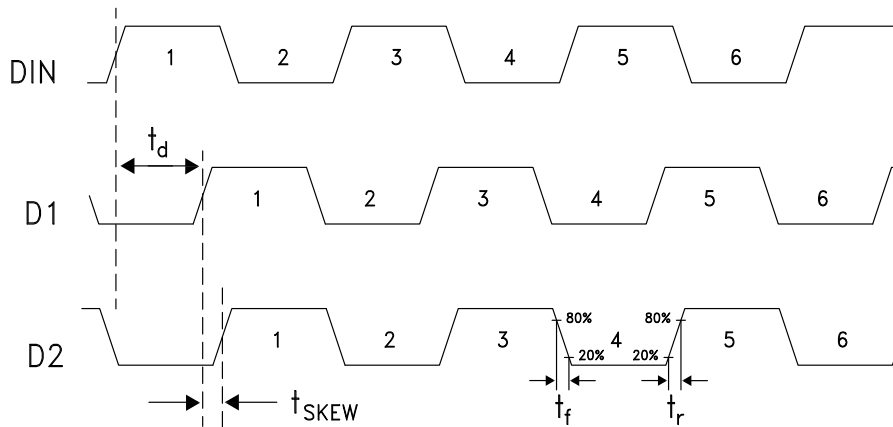
**14 GBPS FAST RISE TIME
1:2 FANOUT BUFFER**

Eye Diagram



[1] Test Conditions:
 Pattern generated with an Agilent N4903A Serial BERT.
 Eye Diagram presented on a Tektronix CSA 8000.
 Device input = 10 Gbps PN code, V_{in} = 300 mVp-p differential.
 Both output channels shown.

Timing Diagram





**14 GBPS FAST RISE TIME
1:2 FANOUT BUFFER**

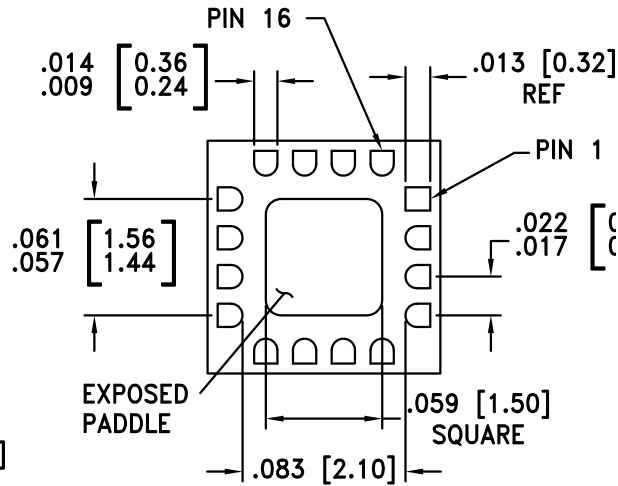
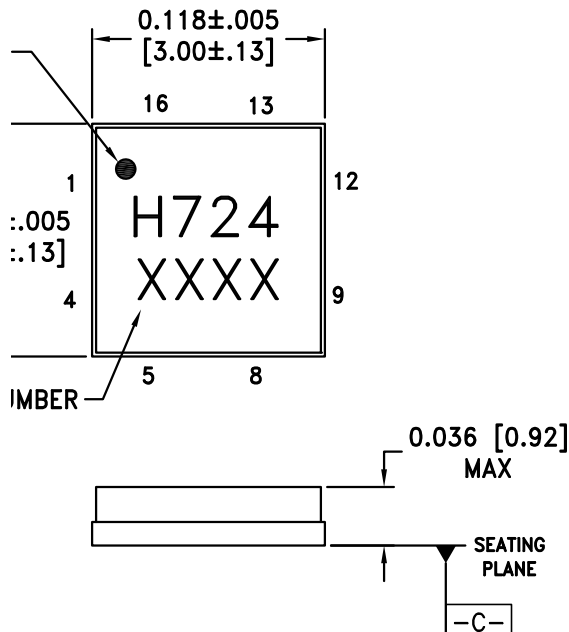
Absolute Maximum Ratings

| | |
|--|-------------------|
| Power Supply Voltage (Vee) | -3.75 V to +0.5 V |
| Input Signals | -2 V to +0.5 V |
| Output Signals | -1.5 V to +1 V |
| Continuous Pdiss (T = 85 °C) (derate 17 mW/°C above 85 °C) | 0.68 W |
| Thermal Resistance (R _{th j-p}) Worst case junction to package paddle | 59 °C/W |
| Maximum Junction Temperature | 125 °C |
| Storage Temperature | -65 °C to +150 °C |
| Operating Temperature | -40 °C to +85 °C |
| ESD Sensitivity (HBM) | Class 1C |



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING:
30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C-
6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
7. PADDLE MUST BE SOLDERED TO GND.


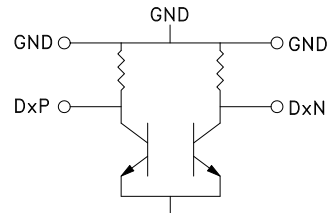
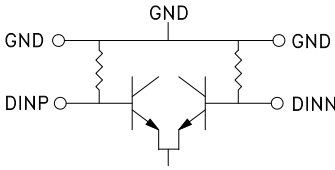

Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking ^[2] |
|-------------|-----------------------|------------------|---------------------|--------------------------------|
| HMC724LC3 | Alumina, White | Gold over Nickel | MSL3 ^[1] | H724 XXXX |

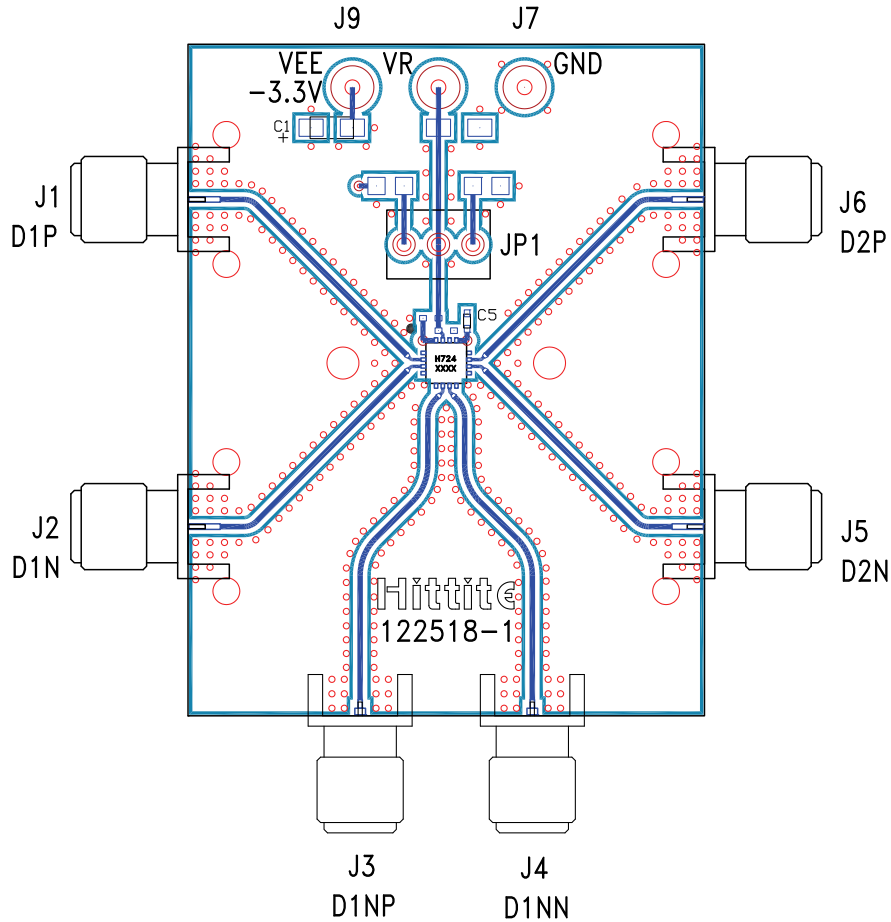
[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX


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Pin Descriptions [1]

| Pin Number | Function | Description | Interface Schematic |
|---------------------|----------------------|--|--|
| 1, 4, 5, 8, 9, 12 | GND | Signal Grounds |  |
| 2, 3 10, 11 | D1P, D1N D2N, D2P | Differential Data Outputs, Current Mode Logic (CML) referenced to positive supply. |  |
| 6, 7 | DINP, DINN | Differential Data Inputs, Current Mode Logic (CML) referenced to positive supply. |  |
| 13, 16 | Vee | Negative Supply | |
| 14, Package Base | GND | Supply Ground |  |
| 15 | N/C | No Connection required. This pin may be connected to RF/DC ground without affecting performance. | |

[1] Contact HMC for alternate pinouts


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Evaluation PCB

List of Materials for Evaluation PCB 122520 [1]

| Item | Description |
|---------|--|
| J1 - J6 | PCB Mount SMA RF Connectors |
| J7, J9 | DC Pin |
| C1 | 4.7 μ F Capacitor, Tantalum |
| C5 | 100 pF, Capacitor 0402 Pkg. |
| U1 | HMC724LC3 High Speed Logic, Fanout Buffer |
| PCB [2] | 122518 Evaluation Board |

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR or Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed packaged base should be connected to GND. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



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Application Circuit

